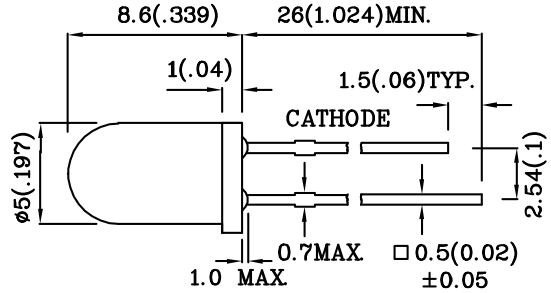
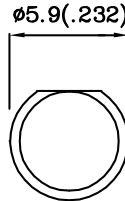


Features

- WIDE VIEWING ANGLE.
- OUTSTANDING MATERIAL EFFICIENCY.
- RELIABLE AND RUGGED.
- I.C.COMPATIBLE/LOW CURRENT CAPABILITY.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

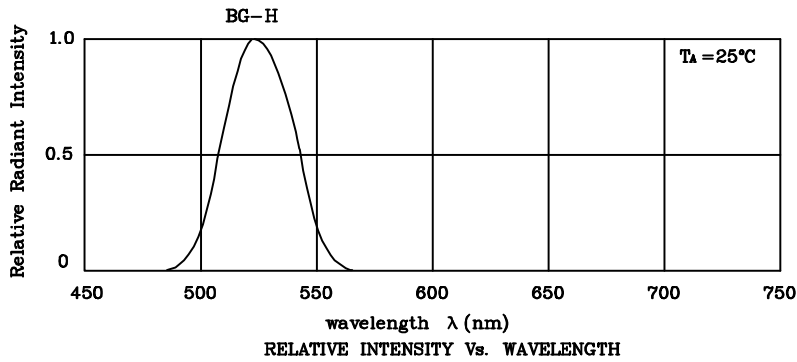
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ " unless otherwise noted.

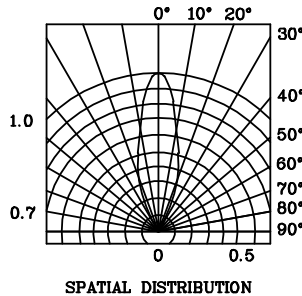
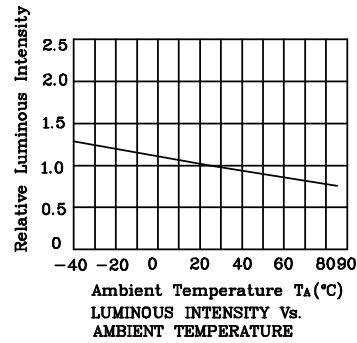
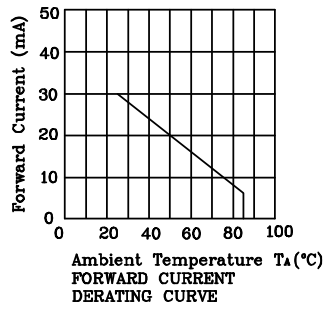
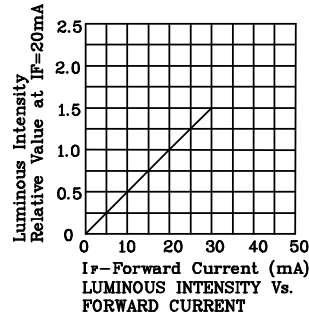
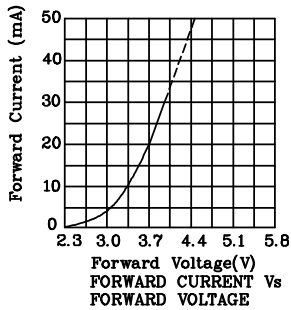
Absolute maximum ratings (TA=25°C)		BG-H (InGaN)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	150	mA
Power Dissipation	PT	120	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		BG-H (InGaN)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	3.7	V
Forward Voltage (Max.) (IF=20mA)	VF	4.1	V
Reverse Current (VR=5V)	IR	10	uA
Wavelength of Peak Emission (IF=20mA)	λP	520	nm
Wavelength of Dominant Emission (IF=20mA)	λD	525	nm
Spectral Line Full Width At Half-Maximum (IF=20mA)	$\Delta\lambda$	35	nm
Capacitance (VF=0V, f=1MHz)	C	45	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λP	Viewing Angle $2\theta 1/2$
				min.	typ.		
XLBGH14W	Green	InGaN	Water Clear	4700	9990	520	30°



❖ **BG-H**



Remarks:

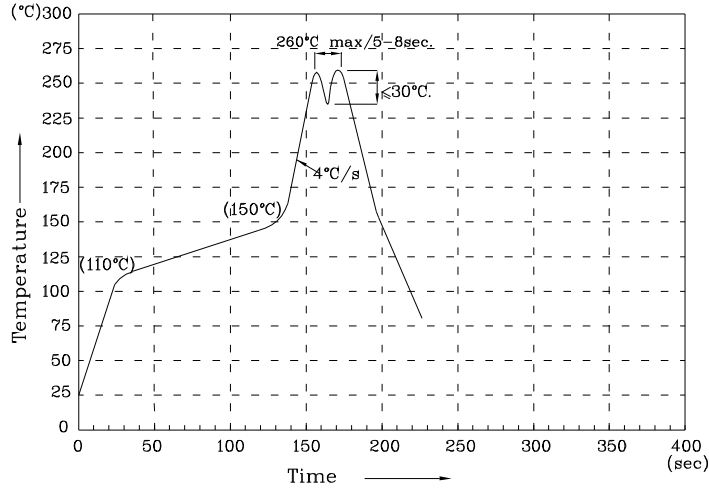
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XLBGH14W

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.